Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
L1	0	@ad<="20031230" and 'chip package' and 'under fill' same 'cured' same 'polymer'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/03/30 15:39
L2	0	@ad<="20031230" and 'chip package' and 'under-fill' same 'polymer' same 'cure'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/03/30 15:40
L3	0	@ad<="20031230" and 'chip package' and 'under-fill' same 'polymer' same 'curing'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/03/30 15:41
L4	5	@ad<="20031230" and 'under-fill' same 'polymer' same 'curing'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/03/30 15:41
L5	65	@ad<="20031230" and 'under fill' same 'polymer'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/03/30 15:41
L6	4	@ad<="20031230" and 'chip package' and 'under fill' same 'polymer'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/03/30 15:41
S1	0	@ad<="20031230" and 'chip package' and 'chip contact pad' and stud' and substrate'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/03/30 15:39
S2	28	@ad<="20031230" and 'chip package' and 'chip contact pad' and 'stud'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/03/30 13:49
S3	45	@ad<="20031230" and 'chip contact pad' and 'stud'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/03/29 09:42
S4	0	arnold-wilson-richard.in.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/03/29 09:51

S5	0	arnold-willson-richard.in.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/03/29 09:59
S6	5	arnold-richard.in.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/03/29 09:56
S7	17	arnold.in. and 'chip package'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/03/29 09:54
S8	0	odegard-anthony-charles.in.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/03/29 09:55
S9	3	odegard-charles.in.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/03/29 09:58
S10	0	cowens--wayne-marvin.in.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/03/29 09:57
S11	0	cowens-wayne-marvin.in.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/03/29 09:57
S12	0	cowens-marvin.in.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/03/29 09:57
S13	301	cowens.in.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/03/29 09:57
S14	0	cowens-w-marvin.in.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/03/29 09:57
S16	7	Cowens-Marvin-W.in.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/03/29 09:59

S17	25	arnold-richard-w.in.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/03/29 10:00
S18	10	@ad<="20031230" and 'chip packaging' and 'stud' with 'mounting'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/03/29 10:09
S19	111	@ad<="20031230" and 'chip packaging' and ('stud' or 'pin') with 'mounting'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/03/29 10:03
S20	1	"20020070459".PN.	US-PGPUB	OR	ON	2005/03/29 10:05
S21	1	"20020048848".PN.	US-PGPUB	OR	ON	2005/03/29 10:05
S22	1	"6650011".PN.	USPAT; USOCR	OR	ON	2005/03/29 10:06
S23	1	"6576499".PN.	USPAT; USOCR	OR	ON	2005/03/29 10:06
S24	2231	@ad<="20031230" and (257/778).ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/03/29 13:34
S25	1850	@ad<="20031230" and (257/779-780).ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/03/29 10:10
S26	1117	@ad<="20031230" and (257/781-782).ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/03/29 10:11
S27	1641	@ad<="20031230" and (257/786).ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/03/29 10:12
S28	4134	@ad<="20031230" and (257/773-775).ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/03/29 10:14
S29	24	@ad<="20031230" and (257/180).ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/03/29 10:15

S30	165	@ad<="20031230" and (257/181-182).ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/03/29 10:16
S31	2120	@ad<="20031230" and (257/676).ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/03/29 10:16
S32	113	@ad<="20031230" and (257/733).ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/03/29 10:50
S33	1445	@ad<="20031230" and (257/777).ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/03/29 10:17
S34	437	@ad<="20031230" and (257/731-732).ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/03/29 10:50
S35	738	@ad<="20031230" and (257/697).ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/03/29 13:35
S36	1569	@ad<="20031230" and (257/690).ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/03/29 13:35
S37	1187	@ad<="20031230" and (257/691).ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/03/29 13:35
S38	1661	@ad<="20031230" and (257/692).ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/03/29 13:36
S39	1307	@ad<="20031230" and (257/693).ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/03/29 13:36
S40	165	@ad<="20031230" and (257/694).ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/03/29 13:36

S41	155	@ad<="20031230" and (257/695). ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/03/29 13:36
S42	948	@ad<="20031230" and (257/696). ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/03/29 13:36
S43	1291	@ad<="20031230" and (257/698). ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/03/29 13:36
S44	125	@ad<="20031230" and (257/699). ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/03/29 13:36
S45	34	@ad<="20031230" and 'pin grid' and 'chip contact pad' and 'substrate'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/03/29 14:01
S46	1641	@ad<="20031230" and 'pin grid' and ('chip' or 'IC') with 'pad'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/03/29 14:02
S47	711	@ad<="20031230" and 'pin grid' and ('chip' or 'IC') with 'pad' same 'pin'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/03/29 14:01
S48	117	@ad<="20031230" and 'pin grid' and 'IC' with 'pad' with 'pin'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/03/29 14:02
S50	67	@ad<="20031230" and 'chip' with 'pad' with 'pin' and 'underfill'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/03/29 14:05
S51	197	@ad<="20031230" and 'PGA' and 'chip' with 'pad' with 'pin'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/03/29 15:31
S52	134	@ad<="20031230" and 'PGA' and 'die' with 'pad' with 'pin'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/03/29 15:50

S53	243	@ad<="20031230" and 'PGA' and 'die' with 'pad' with 'lead'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/03/29 15:50
S54	99	@ad<="20031230" and 'PGA' and 'IC' with 'pad' with 'lead'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/03/30 11:02
S55	2	("4818728").PN.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/03/29 15:50
S56	6	@ad<="20031230" and 'PGA' and 'IC' and 'solder well'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/03/30 14:09
S57	0	@ad<="20031230" and 'pin' same 'solder well' with 'liner'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/03/30 11:03
S58	0	@ad<="20031230" and 'pin' same 'solder well' with 'line'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/03/30 11:03
S59	0	@ad<="20031230" and 'solder well' with 'liner'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/03/30 11:03
S60	5	@ad<="20031230" and 'solder well' with 'trace'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/03/30 11:03
S61	23	@ad<="20031230" and 'solder well' with 'conductive'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/03/30 11:03
S62	0	("("20030198033"|"5349495"|"5561594"|"5650918"|"5926375"|"6013897"|"6016254"|"6271480"|"6555757"|"6590772"|"6606249").PN.").PN.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/03/30 12:03

S63	22	("20030198033"|"5349495"|"556159 4"|"5650918"|"5926375"|"6013897 "|"6016254"|"6271480"|"6555757"|" 6590772"|"6606249").PN.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/03/30 12:03
S64	1	"4949224".PN.	USPAT; USOCR	OR	ON	2005/03/30 12:19
S65	1	"4903889".PN.	USPAT; USOCR	OR	ON	2005/03/30 12:20
S66	10	@ad<="20031230" and 'bonded pin' same 'wire' with 'gold'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/03/30 13:05
S68	0	@ad<="20031230" and 'solder well' with 'conductive adhesive'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/03/30 13:06
S69	243	@ad<="20031230" and 'solder ball' with 'conductive adhesive'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/03/30 13:10
S70	0	@ad<="20031230" and 'solder pastel' with 'conductive adhesive'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/03/30 13:10
S71	316	@ad<="20031230" and 'solder paste' with 'conductive adhesive'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/03/30 13:10
S72	1124	@ad<="20031230" and 'stacked chip'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/03/30 13:51
S73	391	@ad<="20031230" and 'stacked chip' same 'substrate'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/03/30 13:52
S75	163	@ad<="20031230" and 'flip chip' same 'substrate' same 'conductive trace' same 'via'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/03/30 13:55
S76	337	@ad<="20031230" and 'flip chip' and 'substrate' with 'conductive trace' with 'via'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/03/30 13:56

S77	74	@ad<="20031230" and 'flip chip' same 'IC' and 'substrate' with 'conductive trace' with 'via'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/03/30 14:09
S78	52	@ad<="20031230" and 'BGA' same 'IC' and 'substrate' with 'conductive trace' with 'via'	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/03/30 14:09